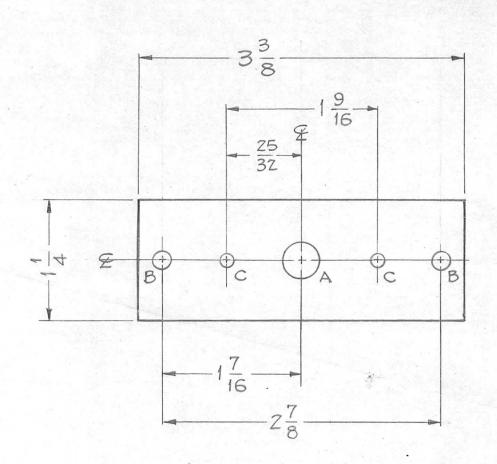
REQ.		USED ON	DVECTA	
PER.	MODEL	ASS'Y. NO.	DATE	UX-56/ A
1	GPT-40K	MODE SW.	7-1-60	INJUIA



HOLES ~  $A \sim \frac{3}{8}$  DIA. I REQ.  $B \sim \frac{3}{16}$  DIA. ZREQ.  $C \sim \frac{9}{64}$  DIA. ZREQ.

## \* FUNGUS PROOFING PER TMC SPECIFICATION S-113

								REQ. ITEM		PART NO.		DESCRIPTION	NO SYI	
44								1/8	" TI	HICK	THE	TECHNICAL	MATERIEL CORP.	
							STOCK SIZE		MAMARONECK, NEW YORK					
A		SII3 ADDED	4-13-64	11186	A·M	No	000	PHENOLIC			INSULATOR,			
SSUE	ITEM	CHANGED FROM	DATE	CH. NO.	DRAFTS CHECKER	FNG APP	MATERIAL		WAFER SWITCH					
TOLERANCES		SCALE: FULL- DO NOT SCALE-				XXXP			J.C.Biele	Lula	25			
DEC. DIM. ±  FRAC. DIM. ± 1/64  ANGULAR DIM. ±		MAXIMUM ALLOWABLE TOLERANCES HAVE BEEN DETERMINED AND ANY DEVIATIONS WILL BE CAUSE FOR REJECTION. REMOVE ALL BURRS AND SHARP EDGES				TYPE & TE	APER.	HEATTREAT. SPEC.	DRAWN	CHECKED	FINAL APPROVAL			
						NATURAL *			arc	PX-567 A				
								ELEC. DES. APP MECH. DES. APP						